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IN THE CLAIMS:

Please cancel claims 11 and 23, without prejudice or disclaimer.

Please cancel claims 26-32, without prejudice or disclaimer, as being drawn to a non-elected invention.

Please substitute the original claims with the amended claims provided below. A copy of the marked up amended claims is attached hereto:

- B1*
- 5/25*
- 7/1*
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1. (once amended) A method of processing a substrate, the method comprising:
providing a substrate in a process chamber, the substrate having a surface;
introducing a gas into the process chamber;
energizing the gas by passing RF energy through a wall of the process chamber at a power sufficient to couple the RF energy from above an external surface of the process chamber to the gas inside the process chamber to energize the gas; and
detecting radiation from directly above the surface of the substrate after the radiation propagates through the wall and the external surface of the process chamber.
2. (once amended) A method according to claim 1 comprising energizing the gas by powering an antenna external to the process chamber at the power.
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10. (once amended) A method of processing a substrate, the method comprising:
 placing a substrate in a process chamber, the substrate having a surface;
 introducing a gas into the process chamber;
B2
 inductively coupling RF energy through a ceiling of the process chamber at a power sufficient to couple the RF energy from above an external surface of the ceiling of the process chamber to the gas inside the process chamber to energize the gas; and
Sig
D1
 detecting radiation from directly above the surface of the substrate after the radiation propagates through a window in the ceiling and the external surface of the process chamber.

- B2*
12. (once amended) A method according to claim 10 comprising
 inductively coupling the RF energy by powering an antenna that (1) is substantially non-vertical, or (2) comprises a planar coil.
B3

- B4*
17. (once amended) A method of processing a substrate, the method comprising:
 providing a chamber having an external surface that is at least partially dome shaped;
 providing a substrate in the chamber, the substrate having a surface;
 introducing a gas into the chamber;
 inductively coupling RF energy at a power sufficient to pass the RF energy from above the at least partially domed external surface to the gas inside the chamber; and
 monitoring radiation from directly above a surface of the substrate that propagates through the at least partially domed external surface during processing of the substrate.

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21. (once amended) A method of processing a substrate, the method comprising:
(Handwritten notes: C, B, S)
surface;
introducing a process gas into the first enclosure;
powering an antenna to inductively coupling RF energy at a power sufficient to pass RF energy from outside an external surface of a ceiling of the first enclosure to the process gas inside the first enclosure to energize the process gas; and monitoring a sufficient intensity of radiation from directly above the surface of the substrate from after the radiation has propagated through the ceiling and external surface of the first enclosure and into a second enclosure disposed above the first enclosure to determine a process endpoint.